

EAST Search History

EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	4	("2003026697").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2011/03/23 13:39
S2	2	("20030026697").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2011/03/23 13:39
S3	9	("2003/0026697").URPN.	USPAT	OR	ON	2011/03/23 13:45
S4	157411	(electroform\$4 electro?form\$4 electroplat\$4 electro?plat\$4 electrol\$4 plated plating anodiz\$3) and (mask\$3 resist etch? stop etching?stop photoresist\$3 photo?resist\$3 (protect\$4 near4 (coat\$4 layer\$4 film))) and (metal metall\$4 conduct\$4 nickel copper cupronickel Cu Ni) and (groove recess hole depression trench channel tunnel slot slit)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/03/23 14:06
S5	24686	(electroform\$4 electro?form\$4 electroplat\$4 electro?plat\$4 electrol\$4 plated plating anodiz\$3) same (mask\$3 resist etch? stop etching?stop photoresist\$3 photo?resist\$3 (protect\$4 near4 (coat\$4 layer\$4 film))) same (metal metall\$4 conduct\$4 nickel copper cupronickel Cu Ni) same (groove recess hole depression trench channel tunnel slot slit)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/03/23 14:07

S6	1359	(29/527.2).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2011/03/23 14:09
S7	14372	(29/527.1,890.09,890.1,825,829,830,592.1).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2011/03/23 14:09
S8	4444	(427/457,58,99.5,105).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2011/03/23 14:10
S9	1441	(204/450,471,485).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2011/03/23 14:10
S10	12136	(electroform\$4 electro?form\$4 electroplat\$4 electro?plat\$4 electrol\$4 plated plating anodiz\$3) with (metal metall\$4 conduct\$4 nickel copper cupronickel Cu Ni) same (mask\$3 resist etch?stop etching?stop photoresist\$3 photo?resist\$3 (protect\$4 near\$4 (coat\$4 layer\$4 film))) with (groove recess hole depression trench channel tunnel slot slit)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/03/23 14:11
S11	6535	(electroform\$4 electro?form\$4 electroplat\$4 electro?plat\$4 electrol\$4 plated plating anodiz\$3) with (metal metall\$4 conduct\$4 nickel copper cupronickel Cu Ni) with (mask\$3 resist etch?stop etching?stop photoresist\$3 photo?resist\$3 (protect\$4 near\$4 (coat\$4 layer\$4 film))) with (groove recess hole depression trench channel tunnel slot slit)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/03/23 14:11

S12	3428	(electroform\$4 electro?form\$4 electroplat\$4 electro?plat\$4 electrol\$4 plated plating anodiz\$3) with (nickel copper cupronickel Cu Ni) with (mask\$3 resist etch?stop etching?stop photoresist\$3 photo?resist\$3 (protect\$4 near\$4 (coat\$4 layer \$4 film))) with (groove recess hole depression trench channel tunnel slot slit)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/03/23 14:12
S13	21436	S6 S7 S8 S9	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/03/23 14:22
S14	930	S5 and S13	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/03/23 14:22
S15	872	S14 and (polish\$3 grind\$3 sand\$3 abra\$4 fil\$3 mill\$3 machin \$3 CMP burnish\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/03/23 14:27
S16	2	("6602053").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2011/03/23 14:34
S17	36	("2641439" "20020141872" "3678570" "3806276" "4528048" "4623087" "4629397" "4769309" "5640767" "5875549" "6203927" "6018950" "6149160").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/03/23 14:37

S18	5265	subramanian.in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/03/23 15:32
S19	3383	(electroform\$4 electro?form\$4 electroplat\$4 electro?plat\$4 electroly\$3 plated plating anodiz\$3) with (nickel copper cupronickel Cu Ni) with (mask\$3 resist etch?stop etching?stop photoresist\$3 photo?resist\$3 (protect\$4 near\$4 (coat\$4 layer\$4 film))) with (groove recess hole depression trench channel tunnel slot slit)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/03/23 16:22
S20	24440	(electroform\$4 electro?form\$4 electroplat\$4 electro?plat\$4 electroly\$3 plated plating anodiz\$3) same (mask\$3 resist etch?stop etching?stop photoresist\$3 photo?resist\$3 (protect\$4 near\$4 (coat\$4 layer\$4 film))) same (metal metall\$4 conduct\$4 nickel copper cupronickel Cu Ni) same (groove recess hole depression trench channel tunnel slot slit)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/03/23 16:23
S21	3110	205/67-79.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/03/23 17:29
S22	208	S21 and (electroform\$4 electro?form\$4 electroplat\$4 electro?plat\$4 electroly\$3 plated plating anodiz\$3) same (mask\$3 resist etch?stop etching?stop photoresist\$3 photo?resist\$3 (protect\$4 near\$4 (coat\$4 layer\$4 film))) same (metal metall\$4 conduct\$4 nickel copper cupronickel Cu Ni) same (groove recess hole depression trench channel tunnel slot slit)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/03/23 17:29
S23	4	("20030026697" "20080246558").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/03/23 17:31
S24	1	(US-4736521-\$.)did.	USPAT	OR	ON	2011/03/23 19:10

S25	1	S24 and (electroform\$4 electro?form\$4 electroplat\$4 electro?plat\$4 electrolysis electrolytic plated plating anodiz\$3) and (mask\$3 resist etch?stop etching?stop photoresist\$3 photo?resist\$3 (protect\$4 near4 (coat\$4 layer\$4 film))) and (metal metall\$4 conduct\$4 nickel copper cupronickel Cu Ni) and (groove recess hole depression trench channel tunnel slot slit)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/03/23 19:11
S26	1	S24 and (electroform\$4 electro?form\$4 electroplat\$4 electro?plat\$4 electrolysis electrolytic anodiz\$3) and (mask\$3 resist etch?stop etching?stop photoresist\$3 photo?resist\$3 (protect\$4 near4 (coat\$4 layer\$4 film))) and (metal metall\$4 conduct\$4 nickel copper cupronickel Cu Ni) and (groove recess hole depression trench channel tunnel slot slit)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/03/23 19:13
S27	1	S24 and (nickel copper cupronickel Cu Ni iron fe cobalt co)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/03/23 21:09
S28	27	(US-20030026697-\$ or US-20020141872-\$).did. or (US-2641439-\$ or US-5640767-\$ or US-6149160-\$ or US-6203927-\$ or US-3625758-\$ or US-3892635-\$ or US-4285780-\$ or US-4205428-\$ or US-4457952-\$ or US-4520052-\$ or US-4521280-\$ or US-4528072-\$ or US-4560991-\$ or US-4736521-\$ or US-4746399-\$ or US-4991285-\$).did. or (US-1857929-\$ or US-3613230-\$).did. or (JP-61254039-\$ or JP-61254038-\$).did. or (DE-3419674-\$ or US-5640767-\$ or WO-9841668-\$ or WO-0046420-\$ or US-6149160-\$).did.	US-PGPUB; USPAT; USOCR; JPO; DERWENT	OR	ON	2011/03/23 21:46
S29	19	S28 and (thick\$4 deep depth wide width)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/03/23 21:46

S30	27	(US-20030026697-\$ or US-20020141872-\$).did. or (US-2641439-\$ or US-5640767-\$ or US-6149160-\$ or US-6203927-\$ or US-3625758-\$ or US-3892635-\$ or US-4285780-\$ or US-4205428-\$ or US-4457952-\$ or US-4520052-\$ or US-4521280-\$ or US-4528072-\$ or US-4560991-\$ or US-4736521-\$ or US-4746399-\$ or US-4991285-\$).did. or (US-1857929-\$ or US-3613230-\$).did. or (JP-61254039-\$ or JP-61254038-\$).did. or (DE-3419674-\$ or US-5640767-\$ or WO-9841668-\$ or WO-0046420-\$ or US-6149160-\$).did.	US-PGPUB; USPAT; USOCR; JPO; DERWENT	OR	ON	2011/03/24 15:15
S31	23	S30 and (removable removability sacrificial\$2 temporar\$4 peel\$4 detachable detachability remove removed removing detach detached detaching sacrifice sacrificed sacrificing dismount\$4 demount\$4 separable separability separate separated separating dissocia\$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/03/24 15:23
S32	23	S30 and (removable removability sacrificial\$2 temporar\$4 peel\$4 detachable detachability remove removed removing detach detached detaching sacrifice sacrificed sacrificing dismount\$4 demount\$4 separable separability separate separated separating dissocia\$4) same (board carrier substrate substratum base plate baseplate)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/03/24 15:37
S33	17	S30 and (removable removability sacrificial\$2 temporar\$4 peel\$4 detachable detachability remove removed removing detach detached detaching sacrifice sacrificed sacrificing dismount\$4 demount\$4 separable separability separate separated separating dissocia\$4) with (board carrier substrate substratum base plate baseplate)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/03/24 15:39
S34	135474	((board carrier substrate dielectric prepreg) same (circuit wiring) PWB PCB) with (removable removability sacrificial\$2 temporar\$4 peel\$4 detachable detachability remove removed removing detach detached detaching sacrifice sacrificed sacrificing dismount\$4 demount\$4 separable separability separate separated separating dissocia\$4) with (board carrier substrate substratum base plate baseplate)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/03/24 15:46

S35	45143	((board carrier substrate dielectric prepreg) same (circuit wiring) PWB PCB) with (removable removability sacrificial\$2 temporar\$4 peel\$4 detachable detachability remove removed removing detach detached detaching sacrifice sacrificed sacrificing dismount\$4 demount\$4 separable separability separate separated separating dissocia\$4) near2 (board carrier substrate substratum base plate baseplate)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/03/24 15:47
S36	31067	((board carrier substrate dielectric prepreg) near2 (circuit wiring) PWB PCB) with (removable removability sacrificial\$2 temporar\$4 peel\$4 detachable detachability remove removed removing detach detached detaching sacrifice sacrificed sacrificing dismount\$4 demount\$4 separable separability separate separated separating dissocia\$4) near2 (board carrier substrate substratum base plate baseplate)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/03/24 15:48
S37	14387	(29/527.1,890.09,890.1,825,829,830,592.1).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2011/03/24 15:48
S38	614	S37 and ((board carrier substrate dielectric prepreg) near2 (circuit wiring) PWB PCB) with (removable removability sacrificial\$2 temporar\$4 peel\$4 detachable detachability remove removed removing detach detached detaching sacrifice sacrificed sacrificing dismount\$4 demount\$4 separable separability separate separated separating dissocia\$4) near2 (board carrier substrate substratum base plate baseplate)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/03/24 15:48
S39	2	("4790902").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2011/03/24 15:49

EAST Search History (Interference)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1	(metall\$4 component provid\$4 surface (electroform\$4 OR electro?form\$4) layer\$4 (resist OR mask) (non?conductive OR dielectric) pattern\$4 (holes OR recesses OR vias) remov\$4 elongat\$4 fill\$4 (thick\$4 OR deep OR depth) machin\$4 uniform\$4 channel).dm.	US-PGPUB; USPAT; UPAD	AND	ON	2011/07/30 14:37

7/ 30/ 2011 2:39:00 PM

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